AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Claims 1-48 (Canceled).

49. (New) An integrated method comprising:

providing a low dielectric material;

applying a first treatment altering a first property of the low dielectric material, the first treatment being a treatment other than a thermal treatment; and

applying a second treatment altering a second property of the treated low dielectric material and producing a lower dielectric material with better mechanical stability.

50. (New) The integrated method of claim 49, wherein applying a first treatment comprises subjecting the low dielectric material to a treatment selected from a group consisting of hydrogen-based plasma, electron beam, ultraviolet radiation, and microwave hydrogen plasma.

51. (New) The integrated method of claim 49, wherein applying a second treatment comprises subjecting the low dielectric material after the first treatment to a treatment selected from a group consisting of hydrogen-based plasma, electron beam, ultraviolet radiation, and carbon-based plasma, microwave hydrogen plasma.

52. (New) An integrated method comprising:

providing a low dielectric material;

applying a first treatment altering a first property of the low dielectric material; and

applying a second treatment altering a second property of the treated low dielectric material and producing a lower dielectric material with better mechanical stability, the second treatment being a treatment other than a thermal treatment.

53. (New) The integrated method of claim 52, wherein applying a first treatment comprises subjecting the low dielectric material to a treatment selected from a group consisting of hydrogen-based plasma, electron beam, high temperature, ultraviolet radiation, and microwave hydrogen plasma.

54. (New) The integrated method of claim 52, wherein applying a second treatment comprises subjecting the low dielectric material after the first treatment to a treatment selected from a group consisting of hydrogen-based plasma, electron beam, ultraviolet radiation, and carbon-based plasma, microwave hydrogen plasma.

55. (New) An integrated method comprising:

providing a low dielectric material;

applying a first treatment altering a first property of the low dielectric material, the first treatment treating the low dielectric material with hydrogen-based plasma; and

applying a second treatment altering a second property of the treated low dielectric material and producing a lower dielectric material with better mechanical stability.

56. (New) The integrated method of claim 55, wherein applying the second treatment comprises treating the low dielectric material with microwave hydrogen plasma.

57. (New) The integrated method of claim 55, wherein applying the second treatment comprises treating the low dielectric material with ultraviolet radiation.

58. (New) An integrated method comprising:

providing a low dielectric material;

applying a first treatment altering a first property of the low dielectric material, the first treatment treating the low dielectric material with ultraviolet radiation; and

applying a second treatment altering a second property of the treated low dielectric material and producing a lower dielectric material with better mechanical stability.

59. (New) The integrated method of claim 58, wherein applying the second treatment comprises treating the low dielectric material with carbon-based plasma.

60. (New) The integrated method of claim 58, wherein applying the second treatment comprises treating the low dielectric material with hydrogen plasma.

61. (New) An integrated method comprising:

providing a low dielectric material;

applying a first treatment altering a first property of the low dielectric material, the first treatment treating the low dielectric material with microwave hydrogen plasma; and

applying a second treatment altering a second property of the treated low dielectric material and producing a lower dielectric material with better mechanical stability.

62. (New) The integrated method of claim 61, wherein applying the second treatment comprises treating the low dielectric material with carbon-based plasma.

63. (New) The integrated method of claim 61, wherein applying the second treatment comprises treating the low dielectric material with hydrogen plasma.

64. (New) An integrated method comprising:

providing a low dielectric material;

applying a first treatment altering a first property of the low dielectric material;

applying a second treatment altering a second property of the treated low dielectric material and producing a lower dielectric material with better mechanical stability; and

wherein one of the first and second treatment comprises treating the low dielectric material with a plasma.

65. (New) An integrated method comprising:

providing a low dielectric material;

applying a first treatment altering a first property of the low dielectric material;

applying a second treatment altering a second property of the treated low dielectric material and producing a lower dielectric material with better mechanical stability; and

wherein one of the first and second treatment comprises treating the low dielectric material with ultraviolet radiation.

66. (New) An integrated method comprising:

providing a low dielectric material;

applying a first treatment altering a first property of the low dielectric material;

applying a second treatment altering a second property of the treated low dielectric material and producing a lower dielectric material with better mechanical stability; and

wherein one of the first and second treatment comprises treating the low dielectric material with an electron beam.

67. (New) An integrated method comprising:

providing a low dielectric material;

applying a first treatment altering a first property of the low dielectric material, the first treatment treating the low dielectric material with high temperature; and

applying a second treatment altering a second property of the treated low dielectric material and producing a lower dielectric material with better mechanical stability, the second treatment treating the low dielectric material with a plasma.